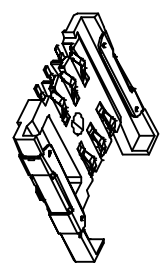
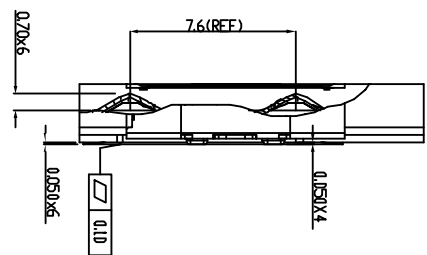
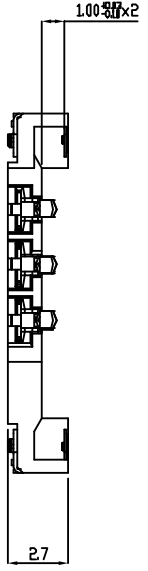
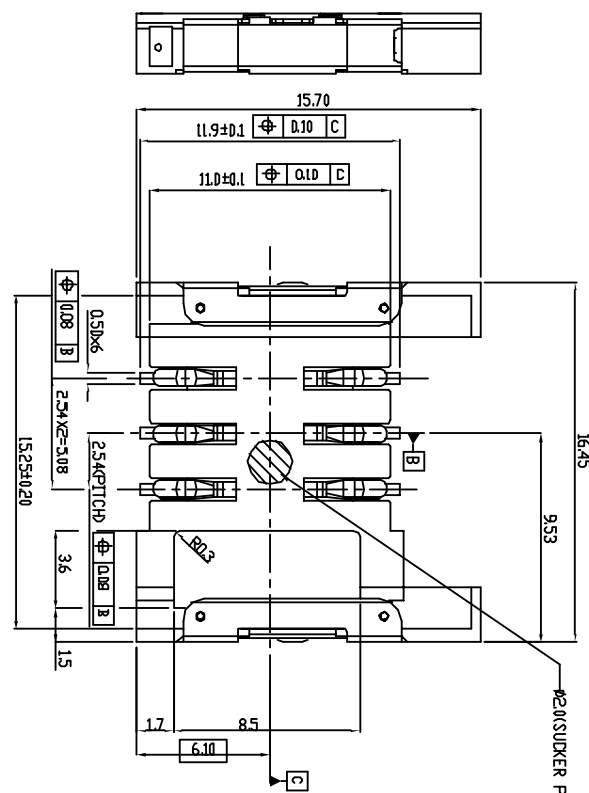
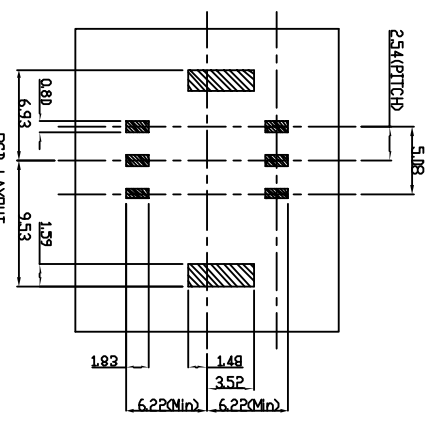


PROJ. NO.  
10042917-XXX

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NOTE: READ COMPATIBLE PRODUCT SPECIFICATIONS  
 a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE. GOLD FLASH PLATING OVER 1.27um MIN NICKEL UNDERPLATE ON SOLDER AREA  
 b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 10 SECONDS IN IR-REFLOW APPLICATION

mat'l. code	tolerances unless otherwise specified		CUSTOMER COPY		title	
lit	sec. no.	dr.	date	XX ±.25	XXX ±.10	0" ±.2"
A	T04-0350	JH	B/19/04	linear	projection	MN
B	T05-0280	JH	12/12/05	angles	product family	SIM CARD
				dr	JASON HSU	B/19/04
				brgt	JASON HSU	B/19/04
				dr	STERLING LIN	B/19/04
				pprd	HC LUV	B/19/04
sheet	revision			scale	N/A	
index	sheet	1				

1. MATERIAL:  
 HOUSING: HIGH TEMPERATURE POLYMER.  
 CONTACTS: COPPER ALLOY.  
 METAL HOLD DOWN: STAINLESS STEEL.

2. FINISH:  
 CONTACTS PLATING: CONTACT AREA :  
 SELECT GOLD OVER MIN 1.25um(50u-inch)Ni  
 SOLDER AREA : MIN 0.025um(1.0u-inch)Ni  
 OVER MIN 1.25um(50u-inch)Ni

3. PART NUMBER DESCRIPTION:  
 10042917-0 0 X LF

PLATING  
 1: 30u" Au  
 2: 10u" Au  
 3: 15u" Au  
 4: GOLD FLASH.

LF: LEAD FREE

ACAD

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cage code  
22526